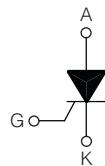
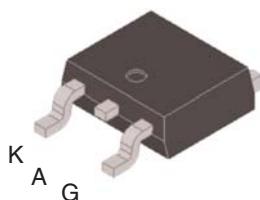


## STANDARD SCR

DPAK  
(Plastic)

**On-State Current**      **Gate Trigger Current**  
12 Amp                  2 mA to 15 mA

**Off-State Voltage**  
200 V ÷ 800 V

These series of **Silicon Controlled Rectifier** use a high performance PNPN technology.

These parts are intended for general purpose applications where high gate sensitivity is required.

## Absolute Maximum Ratings, according to IEC publication No. 134

| SYMBOL       | PARAMETER                       | CONDITIONS   | Value         |  | Unit       |
|--------------|---------------------------------|--|---------------|--|------------|
| $I_{T(RMS)}$ | On-state Current                | 180° Conduction Angle, $T_c = 110^\circ C$             | 12            |  | A          |
| $I_{T(AV)}$  | Average On-state Current        | Half Cycle, $\Theta = 180^\circ$ , $T_c = 110^\circ C$ | 8             |  | A          |
| $I_{TSM}$    | Non-repetitive On-State Current | Half Cycle, 60 Hz                                      | 154           |  | A          |
| $I_{TSM}$    | Non-repetitive On-State Current | Half Cycle, 50 Hz                                      | 140           |  | A          |
| $I^2t$       | Fusing Current                  | $t_p = 10ms$ , Half Cycle                              | 98            |  | $A^2s$     |
| $I_{GM}$     | Peak Gate Current               | 20 $\mu s$ max.  | 4             |  | A          |
| $P_{GM}$     | Peak Gate Dissipation           | 20 $\mu s$ max.  | 10            |  | W          |
| $P_{G(AV)}$  | Gate Dissipation                | 20ms max.  | 1             |  | W          |
| $T_j$        | Operating Temperature           |  | (-40 to +125) |  | $^\circ C$ |
| $T_{stg}$    | Storage Temperature             |  | (-40 to +150) |  | $^\circ C$ |
| $T_{sld}$    | Soldering Temperature           | 10s max.   | 260           |  | $^\circ C$ |
| $V_{RGM}$    | Reverse Gate Voltage            |  | 5             |  | V          |

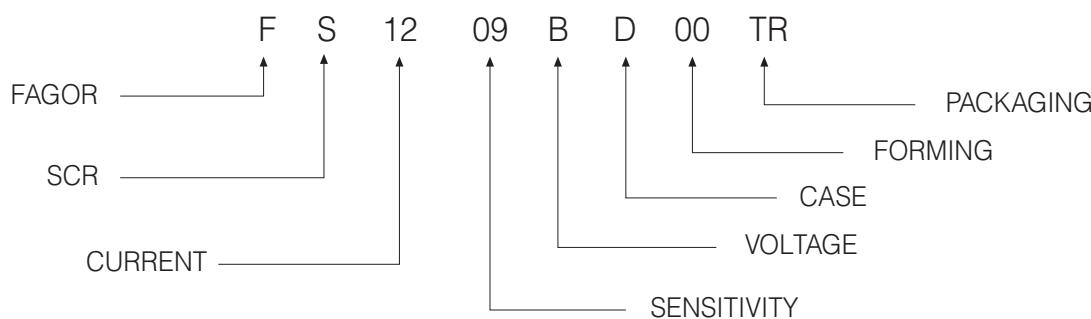
| SYMBOL    | PARAMETER                         | CONDITIONS           | VOLTAGE |     |     |     |     | Unit |
|-----------|-----------------------------------|----------------------|---------|-----|-----|-----|-----|------|
|           |                                   |                      | B       | D   | M   | S   | N   |      |
| $V_{DRM}$ | Repetitive Peak Off State Voltage | $R_{GK} = 1 k\Omega$ | 200     | 400 | 600 | 700 | 800 | V    |
| $V_{RRM}$ |                                   |                      |         |     |     |     |     |      |

## STANDARD SCR

## Electrical Characteristics

| SYMBOL              | PARAMETER                               | CONDITIONS  | SENSITIVITY |         | Uni                          |
|---------------------|---|---|-------------|---------|------------------------------|
|                     |   |   | 09          |         |                              |
| $I_{GT}$            | Gate Trigger Current                    | $V_D = 12 \text{ V}_{DC}, R_L = 140\Omega, T_j = 25^\circ\text{C}$  | MIN<br>MAX  | 2<br>15 | m A                          |
| $V_{GT}$            | Gate Trigger Voltage                    | $V_D = 12 \text{ V}_{DC}, R_L = 140\Omega, T_j = 25^\circ\text{C}$  | MAX         | 1.3     | V                            |
| $V_{GD}$            | Gate Non Trigger Voltage                | $V_D = V_{DRM}, R_L = 3.3k\Omega, R_{GK} = 220\Omega, T_j = 125^\circ\text{C}$  | MIN         | 0.2     | V                            |
| $I_H$               | Holding Current                         | $I_T = 500 \text{ mA}$  | MAX         | 20      | mA                           |
| $I_L$               | Latching Current                        | $I_G = 1.2 I_{GT}$  | MAX         | 40      | mA                           |
| $dV / dt$           | Critical Rate of Voltage Rise           | $V_D = 0.67 \times V_{DRM}, \text{ Gate open } T_j = 125^\circ\text{C}$   | MIN         | 200     | V/ $\mu$ s                   |
| $di / dt$           | Critical Rate of Current Rise           | $I_G = 2 \times I_{GT}, t_r \leq 100 \text{ ns}, f = 60 \text{ Hz}, T_j = 125^\circ\text{C}$                                      | MIN         | 50      | A/ $\mu$ s                   |
| $V_{TM}$            | On-state Voltage                        | at $I_T = 24 \text{ Amp}, t_p = 380 \mu\text{s}, T_j = 25^\circ\text{C}$  | MAX         | 1.6     | V                            |
| $V_{t(o)}$          | Threshold Voltage                       | $T_j = 125^\circ\text{C}$   | MAX         | 0.85    | V                            |
| $r_d$               | Dynamic resistance                      | $T_j = 125^\circ\text{C}$   | MAX         | 32      | $\text{m}\Omega$             |
| $I_{DRM} / I_{RRM}$ | Off-State Leakage Current               | $V_D = V_{DRM}, R_{GK} = 1k\Omega \quad   \quad T_j = 125^\circ\text{C}$<br>$V_R = V_{RRM}, \quad   \quad T_j = 25^\circ\text{C}$ | MAX<br>MAX  | 2<br>5  | $\text{mA}$<br>$\mu\text{A}$ |
| $R_{th(j-c)}$       | Thermal Resistance Junction-Case for DC | for AC 360 ° conduction angle   |             | 1.8     | $^\circ\text{C}/\text{W}$    |
| $R_{th(j-a)}$       | Thermal Resistance Junction-Amb for DC  | $S = 1 \text{ cm}^2$  |             | 70      | $^\circ\text{C}/\text{W}$    |

## PART NUMBER INFORMATION



## STANDARD SCR

Fig. 1: Maximum average power dissipation versus average on-state current.

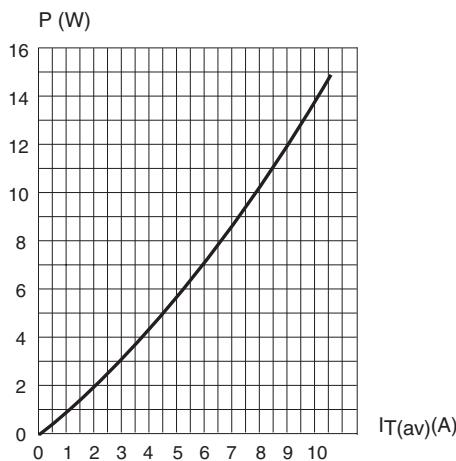


Fig. 2: Average and D.C. on-state current versus case temperature.

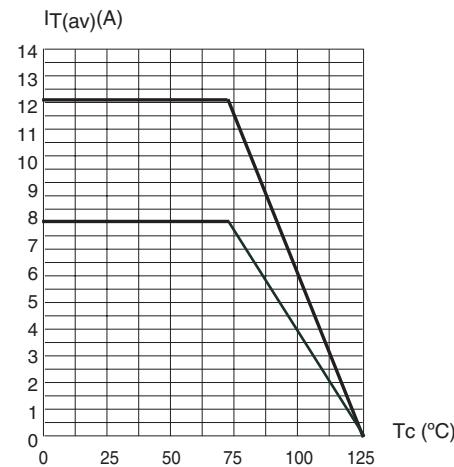


Fig. 3: Relative variation of thermal impedance junction to case versus pulse duration.

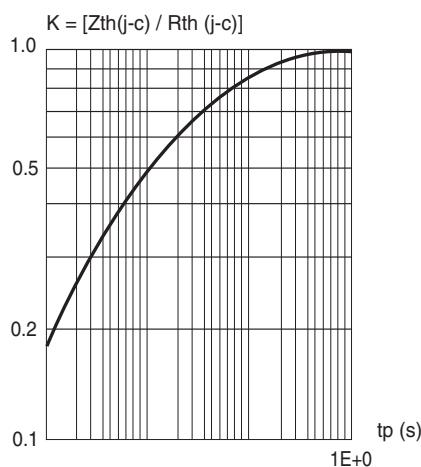


Fig. 5: Non repetitive surge peak on-state current versus number of cycles.

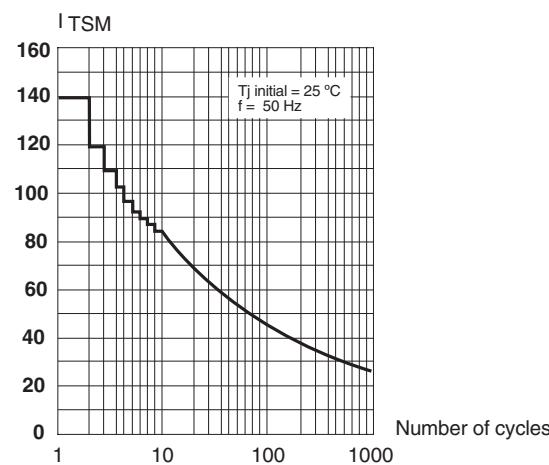


Fig. 4: Relative variation of gate trigger current, holding and latching current versus junction temperature.

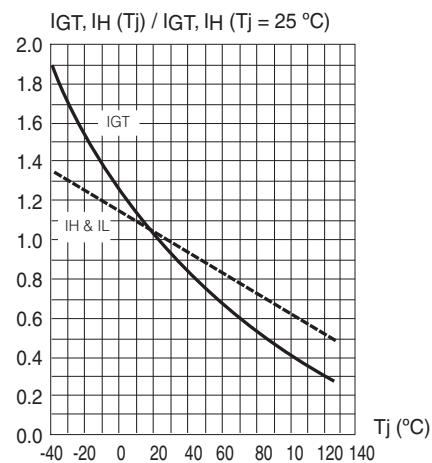
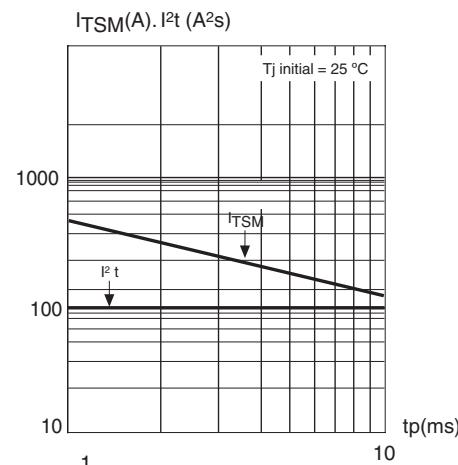


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I<sup>2</sup>t.



**STANDARD SCR**

Fig. 7: On-state characteristics (maximum values).

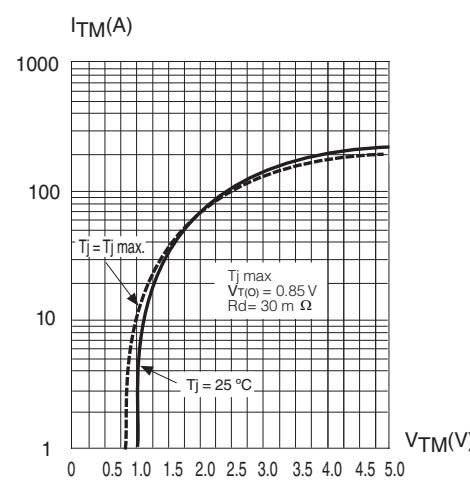


Fig. 8: DPAK RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35 $\mu$ m), full cycle.

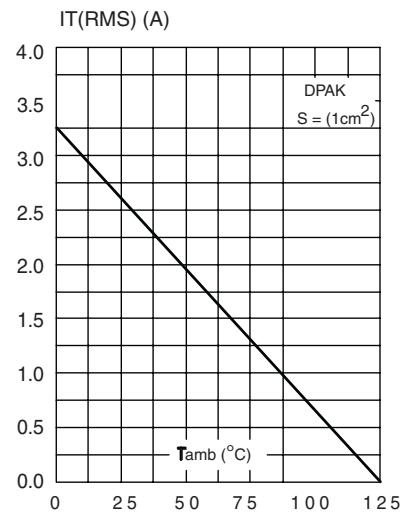
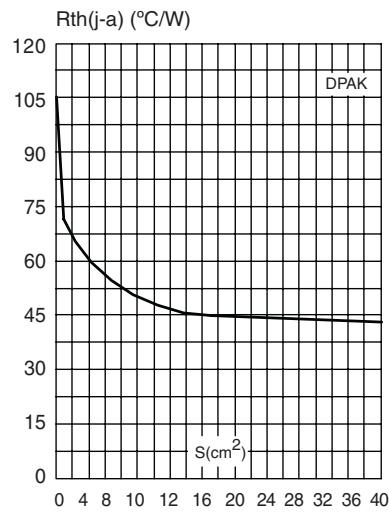
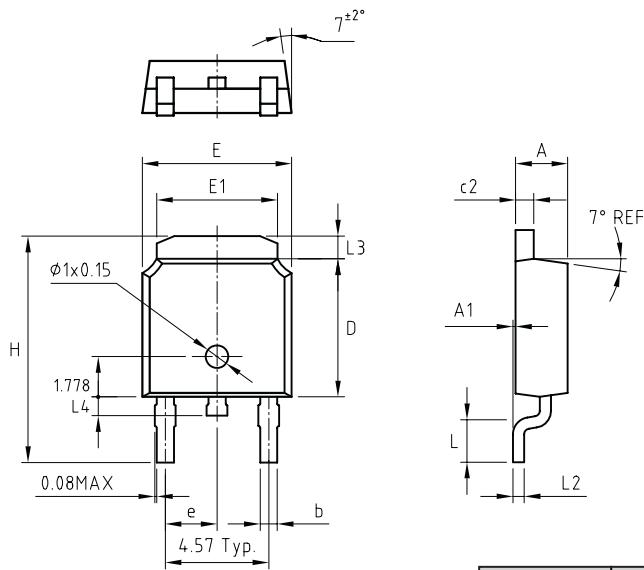


Fig. 9: DPAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FRA, copper thickness: 35 $\mu$ m).



**STANDARD SCR**
**PACKAGE MECHANICAL DATA**
**DPAK / TO252-AA**


| REF. | DIMENSIONS |         |       |
|------|------------|---------|-------|
|      | Min.       | Nominal | Max.  |
| A    | 2.18       | 2.3     | 2.39  |
| A1   | 0          | 0.127   | 0.127 |
| b    | 0.64       | 0.75    | 0.89  |
| c2   | 0.46       | 0.51    | 0.56  |
| D    | 5.97       | 6.1     | 6.22  |
| E    | 6.47       | 6.6     | 6.73  |
| E1   | 5.20       | 5.34    | 5.46  |
| e    |            | 2.28BSC |       |
| H    | 9.77       | 10.03   | 10.28 |
| L    | 1.31       | 1.44    | 1.57  |
| L2   | 0.46       | 0.51    | 0.56  |
| L3   | 0.89       | 1.02    | 1.14  |
| L4   | 0.51       | 0.76    | 1.02  |

Marking: type number

Weight: 0.2 g